

1. Scope :

This specification applies to PIN silicon photodiode chips,
Device No. PD-0131

2. Structure :

- 2-1. Planar type : PIN diode.
- 2-2. Electrodes :
 Top side (Anode) : Aluminum alloy .
 Back side (Cathode) : Gold alloy .

3. Size :

- 3-1. Chip size : 132.0 mils x 132.0 mils (3.353 mm x 3.353 mm).
- 3-2. Chip thickness : 12.0 ± 1.5 mils (0.305 ± 0.038 mm).
- 3-3. Active area : 113.0 mils x 113.0 mils (2.870 mm x 2.870 mm).
- 3-4. Bonding pad (Anode) : 15.0 mils x 15.0 mils (0.381 mm x 0.381 mm).
- 3-5. Pattern drawing : Refer to the attached drawing.

4. Electro-optical characteristics (Ta = 25 °C)

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
**Reverse dark Current	I_D	$V_R=10V$ $E_e=0mW/cm^2$			30	nA
**Reverse breakdown voltage	$V_{(BR)R}$	$I_R=100\mu A$ $E_e=0mW/cm^2$	60			V
Open circuit Voltage	V_{oc}	$T=2856K$ $E_e=5mW/cm^2$		350		mV
Short circuit Current	I_{sc}	$T=2856K$ $E_e=5mW/cm^2$		83		μA
Reverse light Current	I_L	$V_R=5V$ $T=2856K$ $E_e=5mW/cm^2$		85		μA
Total Capacitance	C_t	$V_R=5V$ $E_e=0mW/cm^2$ $f=1MHz$		19		pF

**Based on 100% probing

